Product data sheet

1. General description

Silicon Carbide Schottky diode in a TO252 (DPAK) plastic package, designed for high frequency switched-mode power supplies.



2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability I_{FSM}
- Reduced Losses in Associated MOSFET
- Reduced EMI
- Reduced Cooling Requirements
- RoHS Compliant

3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

4. Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Notes | Values | | | Unit |
|----------------|---------------------------------|--|-------|------------|------|------|------|
| Absolute | maximum rating | | | | | | |
| V_{RRM} | repetitive peak reverse voltage | | | | 650 | | V |
| $I_{F(AV)}$ | average forward current | δ = 0.5 ; square-wave pulse; T _{mb} ≤ 162 °C; Fig. 1; Fig. 2; Fig. 3 | | | 2 | | А |
| T _j | junction temperature | | | -55 to 175 | | °C | |
| Symbol | Parameter | Conditions | Notes | Min | Тур | Max | Unit |
| Static ch | aracteristics | | | | | | |
| V _F | forward voltage | I _F = 2 A; T _j = 25 °C; <u>Fig. 5</u> | | - | 1.26 | 1.40 | V |
| | | I _F = 2 A; T _j = 150 °C; <u>Fig. 5</u> | | - | 1.35 | 1.55 | V |
| Dynamic | characteristics | | | | , | | |
| Q _r | recovered charge | $I_F = 2 \text{ A}; \text{ d}I_F/\text{d}t = 500 \text{ A/}\mu\text{s}; \text{ V}_R = 400 \text{ V};$ $T_i = 25 ^{\circ}\text{C}; \text{ Fig. 7}$ | | - | 4 | - | nC |

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------------------------------|--------------------|----------------|
| 1 | n.c. | not connected | r | К — А |
| 2 | K | cathode [1] | | 001aaa020 |
| 3 | А | anode | <u> </u> | |
| mb | К | mounting base; connected to cathode | | |

^[1] It is not possible to connect to pin 2 of the TO252 package.

6. Ordering information

Table 3. Ordering information

| Type number | Package name | Orderable part number | Packing method | Small packing quantity | Package version | Package issue date |
|--------------|-----------------|-----------------------|----------------|------------------------|-----------------|--------------------|
| WNSC6D02650D | TO252 | WNSC6D02650D6J | Reel | 2500 | TO252NS | 14-Nov-2016 |

7. Marking

Table 4. Marking codes

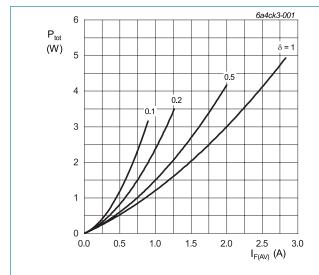
| Type number | Marking codes |
|--------------|------------------|
| WNSC6D02650D | WNSC6D 02650D |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Notes | Values | Unit |
|--------------------|---------------------------------|--|-------|------------|------------------|
| V_{RRM} | repetitive peak reverse voltage | | | 650 | V |
| V _{RWM} | crest working reverse voltage | | | 650 | V |
| V _R | reverse voltage | DC | | 650 | V |
| I _{F(AV)} | average forward current | δ = 0.5; square-wave pulse; T _{mb} ≤ 162 °C; Fig. 1; Fig. 2; Fig. 3 | | 2 | А |
| I _{FRM} | repetitive peak forward current | δ = 0.5; t _p = 25 μs; T _{mb} ≤ 162 °C; square-wave pulse | | 4 | Α |
| I _{FSM} | non-repetitive peak | t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse | | 22 | А |
| | forward current | t_p = 10 µs; $T_{j(init)}$ = 25 °C; square-wave pulse | | 240 | Α |
| l²t | I ² t for fusing | sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$; $t_p = 10 \text{ ms}$ | | 2.42 | A ² s |
| T _{stg} | storage temperature | | | -55 to 175 | °C |
| T _j | junction temperature | | | -55 to 175 | °C |



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$ $V_o = 0.916 \text{ V}; R_s = 0.2923 \Omega$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

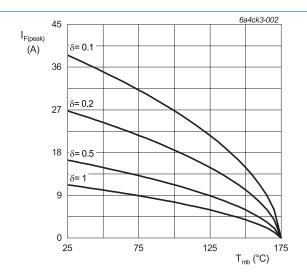
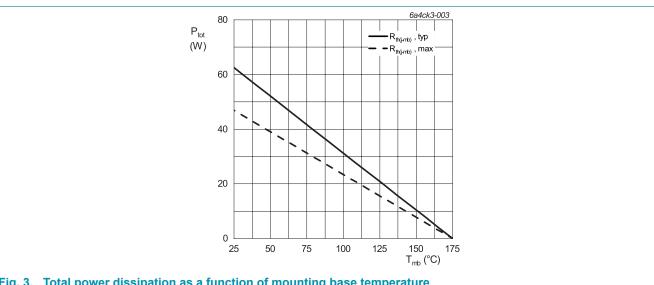


Fig. 2. Current derating as a function of mounting base temperature



9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Notes | Min | Тур | Max | Unit |
|-----------------------|--|--------------------------------|-------|-----|-----|-----|------|
| R _{th(j-mb)} | thermal resistance from junction to mounting base | with heatsink compound; Fig. 4 | | - | 2.4 | 3.2 | K/W |
| $R_{\text{th(j-a)}}$ | thermal resistance from junction to ambient free air | in free air | | - | 60 | - | K/W |

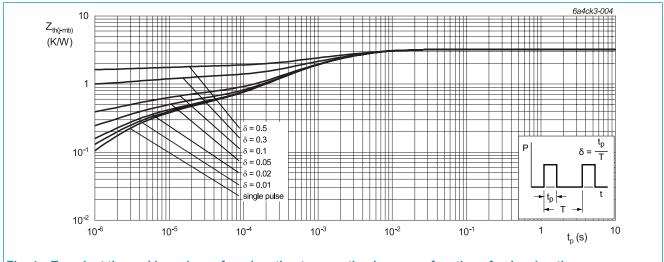
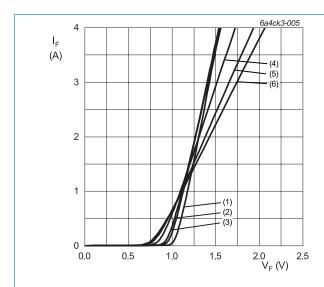


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

| | | | 1 | | | 1 | |
|-----------------|---------------------------------|--|-------|-----|------|------|------|
| Symbol | Parameter | Conditions | Notes | Min | Тур | Max | Unit |
| Static cha | aracteristics | | | | | | |
| V _F | forward voltage | I _F = 2 A; T _j = 25 °C; <u>Fig. 5</u> | | - | 1.26 | 1.40 | V |
| | | I _F = 2 A; T _j = 150 °C; <u>Fig. 5</u> | | - | 1.35 | 1.55 | V |
| | | I _F = 2 A; T _j = 175 °C; <u>Fig. 5</u> | | - | 1.40 | 1.60 | V |
| I _R | reverse current | V _R = 650 V; T _j = 25 °C; <u>Fig. 6</u> | | - | 0.2 | 10 | μA |
| | | V _R = 650 V; T _j = 175 °C; <u>Fig. 6</u> | | - | 3 | 40 | μA |
| Dynamic | characteristics | | | | | | |
| Q_r | recovered charge | $I_F = 2 \text{ A}$; $V_R = 400 \text{ V}$; $dI_F/dt = 500 \text{ A/}\mu\text{s}$; $T_j = 25 \text{ °C}$; Fig. 7 | | - | 4 | - | nC |
| C _d | diode capacitance | f = 1 MHz; V _R = 1 V; T _j = 25 °C | | - | 98 | - | pF |
| | | f = 1 MHz; V _R = 300 V; T _j = 25 °C | | - | 12 | - | pF |
| | | f = 1 MHz; V _R = 600 V; T _j = 25 °C | | - | 10 | - | pF |
| E _{as} | non-repetitive avalanche energy | I _R = 2 A; L = 5 mH; T _{j(init)} = 25 °C | | 9 | - | - | mJ |



 $V_0 = 0.916 \text{ V}; R_s = 0.2923 \Omega$

(1) T_i = -55 °C; typical values

(2) T_i = 0 °C; typical values

(3) T_i = 25 °C; typical values

(4) T_j = 100 °C; typical values (5) T_j = 150 °C; typical values (6) T_j = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

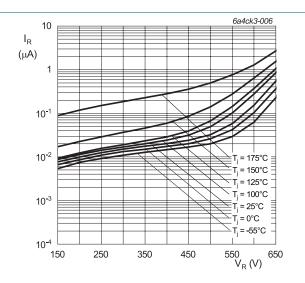
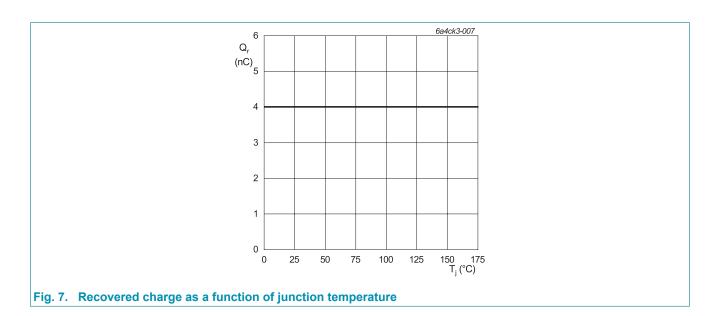
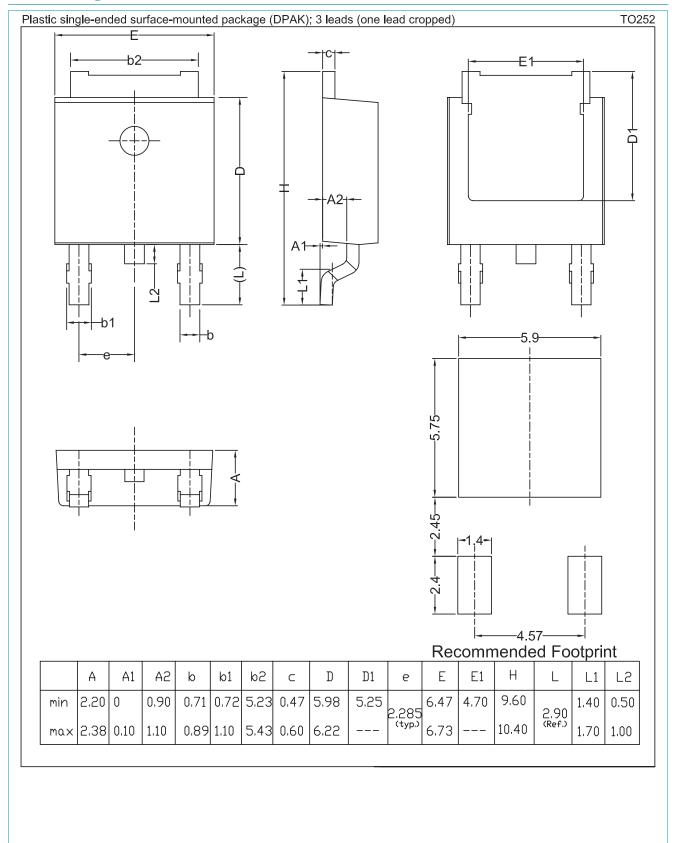


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value



11. Package outline



12. Legal information

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| Document status [1][2] | Product status [3] | Definition |
|--------------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
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| Product [short] data sheet | Production | This document contains the product specification. |

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Product data sheet

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Date of release: 14 April 2023

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